Specification Sheet

**Model No.** : ZJY025

**Description** : 0.96inch OLED Screen resolution 128*64
Size:14*28*1.22mm Driver Chip SH1107 interface SPI/IIC
13Pin Voltage 3.3V Font Color Option White ZJY025
## Revised History

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Revision</th>
<th>Revision Content</th>
<th>Revised on</th>
</tr>
</thead>
<tbody>
<tr>
<td>ZJY025</td>
<td>A</td>
<td>New</td>
<td>20160511</td>
</tr>
<tr>
<td></td>
<td>B</td>
<td>IIC wiring diagram adds pull-up resistor</td>
<td>20170418</td>
</tr>
</tbody>
</table>

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Warranty
Notice
1. **Basic Specifications**

1.1 **Display Specifications**

1) Display Mode: Passive Matrix
2) Display Color: Monochrome (White)
3) Drive Duty: 1/128 Duty

1.2 **Mechanical Specifications**

1) Outline Drawing: According to the annexed outline drawing
2) Number of Pixels: 64 × 128
3) Panel Size: 14 × 28 × 1.22 (mm)
4) Active Area: 10.86 × 21.74 (mm)
5) Pixel Pitch: 0.17 × 0.17 (mm)
6) Pixel Size: 0.15 × 0.15 (mm)
7) Weight: TBD

1.3 **Active Area / Memory Mapping & Pixel Construction**

![Diagram showing active area and memory mapping]

- "A"
- Scale (10:1)
- Details: C32, C95, S126, S127, S0, S1
- Pixel Pitch 0.15 mm
- Pixel Size 0.17 mm
Notes:
1. Color: White
2. Driver IC: SH1107
3. FPC Number: QT1107P01
4. Interface: 4-wire SPI, I2C
5. General Tolerance: ±0.30

Customer Approval
Signature
ICbanQ Inc.

Material
Panel / E.E.E.
Soda Lime / Polyimide

Part
Part
26
27
26
27

S127
S126
C9
C8

P0.7X(13-1)=8.4±0.05
P0.17X128-0.02=21.74
P0.17X64-0.02=10.86

±0.2(Polarizer)
±0.2(Panel Size)
±0.2(Polarizer)

±0.1
±0.15
±0.2(CAP Size)

±0.03
0.1±0.5
0.1±0.7
0.1±0.5
0.1±0.7
0.3±0.0.05
0.1±0.5
0.1±0.7
0.9±0.0.1
0.5±0.5
1.07
1.57
1.88/V/A
0.06
0.06
640x128(x) 0.96”

0.5
1.22±0.1
2±0.15
12±0.2
10±0.2
5±0.2(Polarizer)
14±0.2(CAP Size)
14±0.2(Polarizer)
15.8±0.2
5±0.2
4±0.2
3±0.2
2±0.2
1±0.2
0.17
0.17±0.03

2×128 Monochrome, COG Package

ZFY025 Folding Type OEL Display Module
Part Number: 64 x 128, Monochrome, COG Package

Item
Date
Remark
A
20160421
Original Drawing
## 1.5 Pin Definition

### Power Supply

<table>
<thead>
<tr>
<th>Pin Number</th>
<th>Symbol</th>
<th>I/O</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>2</td>
<td>VPP</td>
<td>P</td>
<td>Power Supply for OEL backlight. Several pins are connected to external power supply.</td>
</tr>
<tr>
<td>4</td>
<td>VDD</td>
<td>P</td>
<td>Power Supply for Logic. Several pins are connected to external power supply.</td>
</tr>
<tr>
<td>12</td>
<td>VSS</td>
<td>P</td>
<td>Ground of OEL System. Several pins are connected to external ground.</td>
</tr>
</tbody>
</table>

### Driver

<table>
<thead>
<tr>
<th>Pin Number</th>
<th>Symbol</th>
<th>I/O</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>6</td>
<td>IREF</td>
<td>I</td>
<td>Current Reference for Brightness Adjustment. A resistor should be connected between this pin and VSS. Set the current at 12.5μA maximum.</td>
</tr>
<tr>
<td>3</td>
<td>VCOMH</td>
<td>O</td>
<td>Voltage Output High Level for COM Signal. Several pins are connected to external power supply.</td>
</tr>
</tbody>
</table>

### Interface

<table>
<thead>
<tr>
<th>Pin Number</th>
<th>Symbol</th>
<th>I/O</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>5</td>
<td>IM1</td>
<td>I</td>
<td>Communication Protocol Select. Several pins are connected to MCU interface selection input. See the following table:</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td><strong>IM1</strong></td>
</tr>
<tr>
<td></td>
<td></td>
<td>4-wire SPI</td>
<td>0</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I2C</td>
<td>1</td>
</tr>
<tr>
<td>8</td>
<td>RES#</td>
<td>I</td>
<td>Power Reset for Controller and Driver. When the pin is low, initialization of the chip is executed. Keep this pin pull high during normal operation.</td>
</tr>
<tr>
<td>7</td>
<td>CS#</td>
<td>I</td>
<td>Chip Select. Several pins are connected to external power supply.</td>
</tr>
<tr>
<td>9</td>
<td>A0</td>
<td>I</td>
<td>Data/Command Control. Several pins are connected to external power supply. When the pin is high and serial interface mode is selected, the data at SI will be transferred to the command register. When it is pulled low, the data at SI will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams.</td>
</tr>
<tr>
<td>10,11</td>
<td>D0,D1</td>
<td>I/O</td>
<td>Serial Data Input/Output and Clock. When serial mode is selected, D1 will be the serial data input SI and D0 will be the serial clock input SCL. When I2C mode is selected, D1 be the serial data input SDA and D0 is the serial clock input, SCL.</td>
</tr>
</tbody>
</table>

### Reserve

<table>
<thead>
<tr>
<th>Pin Number</th>
<th>Symbol</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>1,13</td>
<td>NC</td>
<td>Reserved Pins. Several pins are connected to external power supply. The N.C. pins between function pins are reserved for compatible and flexible design.</td>
</tr>
</tbody>
</table>

---

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2. **Absolute Maximum Ratings**

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
<th>Notes</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply Voltage for Logic</td>
<td>V\textsubscript{DD}</td>
<td>-0.3</td>
<td>3.6</td>
<td>V</td>
<td>1, 2</td>
</tr>
<tr>
<td>Supply Voltage for Display</td>
<td>V\textsubscript{PP}</td>
<td>7</td>
<td>16.5</td>
<td>V</td>
<td>1, 2</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>T\textsubscript{OP}</td>
<td>-40</td>
<td>70</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>T\textsubscript{STG}</td>
<td>-40</td>
<td>85</td>
<td>°C</td>
<td>3</td>
</tr>
<tr>
<td>Life Time (150 cd/m\textsuperscript{2})</td>
<td></td>
<td>10,000</td>
<td>-</td>
<td>hour</td>
<td>4</td>
</tr>
</tbody>
</table>

Note 1: All the above voltages are on the basis of “V\textsubscript{SS} = 0V”.

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. “Optics & Electrical Characteristics”. If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: The defined temperature ranges do not include the polarizer. The maximum withstood temperature of the polarizer should be 80°C.

Note 4: End of lifetime is specified as 50% of initial brightness reached. The reference average operation life time at room temperature is estimated by the accelerated at high temperature conditions.
### 3. Optics & Electrical Characteristics

#### 3.1 Optics Characteristics

<table>
<thead>
<tr>
<th>Characteristics</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Brightness</td>
<td>$L_{br}$</td>
<td>Note 4</td>
<td>120</td>
<td>160</td>
<td>-</td>
<td>cd/m²</td>
</tr>
<tr>
<td>(V_{PP} Supplied Externally)</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>C.I.E. (White)</td>
<td>(x)</td>
<td>C.I.E. 1931</td>
<td>0.25</td>
<td>0.29</td>
<td>0.33</td>
<td></td>
</tr>
<tr>
<td></td>
<td>(y)</td>
<td></td>
<td>0.27</td>
<td>0.31</td>
<td>0.35</td>
<td></td>
</tr>
<tr>
<td>Dark Room Contrast</td>
<td>CR</td>
<td></td>
<td>&gt;10000:1</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Viewing Angle</td>
<td></td>
<td>Free</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>degree</td>
</tr>
</tbody>
</table>

* Optical measurement taken at $V_{DD} = 2.8V$, $V_{PP} = 9V$.  
  Software configuration follows Section 4.5 Initialization.

#### 3.2 DC Characteristics

<table>
<thead>
<tr>
<th>Characteristics</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply Voltage for Logic</td>
<td>$V_{DD}$</td>
<td></td>
<td>1.65</td>
<td>2.8</td>
<td>3.5</td>
<td>V</td>
</tr>
<tr>
<td>Supply Voltage for Display</td>
<td>$V_{PP}$</td>
<td>Note 5</td>
<td>8.5</td>
<td>9.0</td>
<td>9.5</td>
<td>V</td>
</tr>
<tr>
<td>High Level Input</td>
<td>$V_{IH}$</td>
<td>$I_{OUT} = 100\mu A, 3.3MHz$</td>
<td>0.8×$V_{DD}$</td>
<td>-</td>
<td>$V_{DD}$</td>
<td>V</td>
</tr>
<tr>
<td>Low Level Input</td>
<td>$V_{IL}$</td>
<td>$I_{OUT} = 100\mu A, 3.3MHz$</td>
<td>0</td>
<td>-</td>
<td>0.2×$V_{DD}$</td>
<td>V</td>
</tr>
<tr>
<td>High Level Output</td>
<td>$V_{OH}$</td>
<td>$I_{OUT} = 100\mu A, 3.3MHz$</td>
<td>0.8×$V_{DD}$</td>
<td>-</td>
<td>$V_{DD}$</td>
<td>V</td>
</tr>
<tr>
<td>Low Level Output</td>
<td>$V_{OL}$</td>
<td>$I_{OUT} = 100\mu A, 3.3MHz$</td>
<td>0</td>
<td>-</td>
<td>0.2×$V_{DD}$</td>
<td>V</td>
</tr>
<tr>
<td>Operating Current for $V_{Cl}$</td>
<td>$I_{DD}$</td>
<td></td>
<td>-</td>
<td>55</td>
<td>100</td>
<td>μA</td>
</tr>
<tr>
<td>Operating Current for $V_{PP}$</td>
<td>$I_{PP}$</td>
<td>Note 6</td>
<td>-</td>
<td>11</td>
<td>16</td>
<td>mA</td>
</tr>
<tr>
<td>Sleep Mode Current for $V_{DD}$</td>
<td>$I_{DD, SLEEP}$</td>
<td></td>
<td>-</td>
<td>0.1</td>
<td>5</td>
<td>μA</td>
</tr>
<tr>
<td>Sleep Mode Current for $V_{PP}$</td>
<td>$I_{PP, SLEEP}$</td>
<td></td>
<td>-</td>
<td>0.5</td>
<td>5</td>
<td>μA</td>
</tr>
</tbody>
</table>

Note 5 & 6: Brightness ($L_{br}$) and Supply Voltage for Display ($V_{PP}$) are subject to the change of the panel characteristics and the customer’s request.

Note 6: $V_{DD} = 2.8V$, $V_{PP} = 9.0V$, 100% Display Area Turn on.

* Software configuration follows Section 4.5 Initialization.
3.3 AC Characteristics

3.3.3.1 Serial Interface Timing Characteristics: (4-wire SPI)

\((V_{DD} - V_{SS} = 1.65V \text{ to } 2.4V, \ T_a = 25^\circ C)\)

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Description</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>(t_{SCYC})</td>
<td>Serial Clock Cycle Time</td>
<td>500</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{AS})</td>
<td>Address Setup Time</td>
<td>300</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{AH})</td>
<td>Address Hold Time</td>
<td>300</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{DS})</td>
<td>Data Setup Time</td>
<td>200</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{DH})</td>
<td>Data Hold Time</td>
<td>200</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{SS})</td>
<td>Chip Select Setup Time</td>
<td>240</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{SH})</td>
<td>Chip Select Hold Time</td>
<td>120</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{SW})</td>
<td>Serial Clock H Pulse Width</td>
<td>200</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{LW})</td>
<td>Serial Clock L Pulse Width</td>
<td>200</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_r)</td>
<td>Rise Time</td>
<td>-</td>
<td>30</td>
<td>ns</td>
</tr>
<tr>
<td>(t_f)</td>
<td>Fall Time</td>
<td>-</td>
<td>30</td>
<td>ns</td>
</tr>
</tbody>
</table>

\((V_{DD} - V_{SS} = 2.4V \text{ to } 3.5V, \ T_a = 25^\circ C)\)

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Description</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>(t_{SCYC})</td>
<td>Serial Clock Cycle Time</td>
<td>250</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{AS})</td>
<td>Address Setup Time</td>
<td>150</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{AH})</td>
<td>Address Hold Time</td>
<td>150</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{DS})</td>
<td>Data Setup Time</td>
<td>100</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{DH})</td>
<td>Data Hold Time</td>
<td>100</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{SS})</td>
<td>Chip Select Setup Time</td>
<td>120</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{SH})</td>
<td>Chip Select Hold Time</td>
<td>60</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{SW})</td>
<td>Serial Clock H Pulse Width</td>
<td>100</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_{LW})</td>
<td>Serial Clock L Pulse Width</td>
<td>100</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>(t_r)</td>
<td>Rise Time</td>
<td>-</td>
<td>15</td>
<td>ns</td>
</tr>
<tr>
<td>(t_f)</td>
<td>Fall Time</td>
<td>-</td>
<td>15</td>
<td>ns</td>
</tr>
</tbody>
</table>
3.3.3.2 4-wire Serial Interface

(Special Tips):
(When design main board, Please add Electronic Switch circuit, otherwise, will be caused leak current)

Recommended Components:
C1: 0.1μF / 6.3V, X5R
C2: 4.7μF / 6.3V, X5R
C3: 2.2μF / 16V, X7R
C4: 4.7μF / 16V, X7R
C5: 0.1μF / 16V, X7R
R3: 560kΩ, R3 = (Voltage at IREF - VSS) / IREF
R2, R1: 47kΩ
Q1: FDN338P
Q2: FDN335N

Notes:
VDD: 1.65~3.5V, it should be equal to MPU I/O voltage.
Vpp_in: 8.5~9.5V
### 3.3.4.1 I2C Interface Timing Characteristics:

(Vdd = 1.65 - 3.5V, TA = +25°C)

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
<th>Condition</th>
</tr>
</thead>
<tbody>
<tr>
<td>tSCL</td>
<td>SCL clock frequency</td>
<td>DC</td>
<td>-</td>
<td>400</td>
<td>kHz</td>
<td></td>
</tr>
<tr>
<td>tLOW</td>
<td>SCL clock Low pulse width</td>
<td>1.3</td>
<td>-</td>
<td>-</td>
<td>µs</td>
<td></td>
</tr>
<tr>
<td>tHIGH</td>
<td>SCL clock H pulse width</td>
<td>0.6</td>
<td>-</td>
<td>-</td>
<td>µs</td>
<td></td>
</tr>
<tr>
<td>tSU:DATA</td>
<td>data setup time</td>
<td>100</td>
<td>-</td>
<td>-</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>tHLD:DATA</td>
<td>data hold time</td>
<td>0</td>
<td>-</td>
<td>0.9</td>
<td>µs</td>
<td></td>
</tr>
<tr>
<td>Tr</td>
<td>SCL + SDA rise time</td>
<td>20+0.1Cb</td>
<td>-</td>
<td>300</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>Tf</td>
<td>SCL + SDA fall time</td>
<td>20+0.1Cb</td>
<td>-</td>
<td>300</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>Cb</td>
<td>Capacity load on each bus line</td>
<td>-</td>
<td>-</td>
<td>400</td>
<td>pF</td>
<td></td>
</tr>
<tr>
<td>tSU:START</td>
<td>Setup time for re-START</td>
<td>0.6</td>
<td>-</td>
<td>-</td>
<td>µs</td>
<td></td>
</tr>
<tr>
<td>tHLD:START</td>
<td>START Hold time</td>
<td>0.6</td>
<td>-</td>
<td>-</td>
<td>µs</td>
<td></td>
</tr>
<tr>
<td>tSU:STOP</td>
<td>Setup time for STOP</td>
<td>0.6</td>
<td>-</td>
<td>-</td>
<td>µs</td>
<td></td>
</tr>
<tr>
<td>tBUF</td>
<td>Bus free times between STOP and START condition</td>
<td>1.3</td>
<td>-</td>
<td>-</td>
<td>µs</td>
<td></td>
</tr>
</tbody>
</table>
3.3.4.2 \( \text{I}^2\text{C Interface Characteristics} \)

**(Special Tips):**

(When design main board, Please add Electronic Switch circuit, otherwise, will be caused leak current)

**Recommended Components:**

- \( C_1 \): 0.1\( \mu \)F / 6.3V, X5R
- \( C_2 \): 4.7\( \mu \)F / 6.3V, X5R
- \( C_3 \): 4.7\( \mu \)F / 16V, X7R
- \( C_4 \): 4.7\( \mu \)F / 16V, X7R
- \( C_5 \): 0.1\( \mu \)F / 16V, X7R
- \( R_3 \): 560kΩ, \( R_3 = (\text{Voltage at IREF} - \text{VSS}) / \text{IREF} \)
- \( R_2, R_1 \): 47kΩ
- \( R_4, R_5 \): 4.7 kΩ
- \( Q_1 \): FDN338P
- \( Q_2 \): FDN335N

**Notes:**

- \( \text{VDD} \): 1.65~3.5V, it should be equal to MPU I/O voltage.
- \( \text{Vpp_in} \): 8.5~9.5V

www.icbanq.com
4. Functional Specification
4.1 Commands
Refer to the Technical Manual for the SH1107

4.2 Power down and Power up Sequence
To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

4.2.1 Power up Sequence:
1. Power up VDD
2. Send Display off command
3. Initialization
4. Clear Screen
5. Power up VPP
6. Delay 100ms (When VPP is stable)
7. Send Display on command

4.2.2 Power down Sequence:
1. Send Display off command
2. Power down VPP
3. Delay 100ms (When VPP is reach 0 and panel is completely discharges)
4. Power down VDD

Note 9:
1) Since an ESD protection circuit is connected between VDD and VBPPB inside the driver IC, VPP becomes lower than VDD whenever VBDDB is ON and VPP is OFF.
2) VPPB should be kept float (disable) when it is OFF.
3) Power Pins (VDD, VPP) can never be pulled to ground under any circumstance.
4) VBDDDB should not be power down before VPP power down.

4.3 Reset Circuit
When RESB input is low, the chip is initialized with the following status:
1. Display is OFF. Common and Segment are in high impedance state.
2. 128’128 Display Mode
3. Normal segment and display data column and row address mapping (SEG0 is mapped to the top line of the display).
4. Shift register data clear in serial interface
5. Column address counter is set at 0
6. Normal scan direction of the COM outputs
7. Contrast control register is set at 80h
8. Internal DC-DC is selected
4.4 Actual Application Example
Command usage and explanation of an actual example

4.4.1 $V_{pp}$ Supplied Externally

If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

*Power down Sequence*

If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

*Power up Sequence*
External setting

```
void sh1107()
{
    write_i(0xAE);  /*display off*/
    write_i(0x00);  /*set lower column address*/
    write_i(0x10);  /*set higher column address*/
    write_i(0xB0);  /*set page address*/
    write_i(0xdc);  /*set display start line*/
    write_i(0x81);  /*contract control*/
    write_i(0x2f);  /*128*/
    write_i(0x20);  /* Set Memory addressing mode (0x20/0x21) */
    write_i(0xA0);  /*set segment remap*/
    write_i(0xC0);  /*Com scan direction*/
    write_i(0xA4);  /*Disable Entire Display On (0xA4/0xA5)*/
    write_i(0xA6);  /*normal / reverse*/
}
```
```c
write_i(0xA8);    /*multiplex ratio*/
write_i(0x3F);    /*duty = 1/64*/
write_i(0xD3);    /*set display offset*/
write_i(0x60);
write_i(0xD5);    /*set osc division*/
write_i(0x51);
write_i(0xD9);    /*set pre-charge period*/
write_i(0x22);
write_i(0xdb);    /*set vcomh*/
write_i(0x35);
write_i(0xad);    /*set charge pump enable*/
write_i(0x8a);    /*Set DC-DC enable (a=0:disable; a=1:enable) */
write_i(0xAF);    /*display ON*/
```

5. Reliability

5.1 Contents of Reliability Tests

<table>
<thead>
<tr>
<th>Item</th>
<th>Conditions</th>
<th>Criteria</th>
</tr>
</thead>
<tbody>
<tr>
<td>High Temperature Operation</td>
<td>70°C, 240 hrs</td>
<td>The operational functions work.</td>
</tr>
<tr>
<td>Low Temperature Operation</td>
<td>-40°C, 240 hrs</td>
<td></td>
</tr>
<tr>
<td>High Temperature Storage</td>
<td>85°C, 240 hrs</td>
<td></td>
</tr>
<tr>
<td>Low Temperature Storage</td>
<td>-40°C, 240 hrs</td>
<td></td>
</tr>
<tr>
<td>High Temperature/Humidity Operation</td>
<td>60°C, 90% RH, 120 hrs</td>
<td></td>
</tr>
<tr>
<td>Thermal Shock</td>
<td>-40°C ⇔ 85°C, 24 cycles</td>
<td></td>
</tr>
</tbody>
</table>

* The samples used for the above tests do not include polarizer.
* No moisture condensation is observed during tests.

5.2 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
6. **Outgoing Quality Control Specifications**

6.1 **Environment Required**

Customer’s test & measurement are required to be conducted under the following conditions:
- Temperature: 23 ± 5°C
- Humidity: 55 ± 15% RH
- Fluorescent Lamp: 30W
- Distance between the Panel & Lamp: ≥ 50cm
- Distance between the Panel & Eyes of the Inspector: ≥ 30cm
- Finger glove (or finger cover) must be worn by the inspector.
- Inspection table or jig must be anti-electrostatic.

6.2 **Sampling Plan**

Level II, Normal Inspection, Single Sampling, MIL-STD-105E

6.3 **Criteria & Acceptable Quality Level**

<table>
<thead>
<tr>
<th>Partition</th>
<th>AQL</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Major</td>
<td>0.65</td>
<td>Defects in Pattern Check (Display On)</td>
</tr>
<tr>
<td>Minor</td>
<td>1.0</td>
<td>Defects in Cosmetic Check (Display Off)</td>
</tr>
</tbody>
</table>

6.3.1 Cosmetic Check (Display Off) in Non-Active Area

<table>
<thead>
<tr>
<th>Check Item</th>
<th>Classification</th>
<th>Criteria</th>
</tr>
</thead>
<tbody>
<tr>
<td>Panel General Chipping</td>
<td>Minor</td>
<td>X &gt; 6 mm (Along with Edge) Y &gt; 1 mm (Perpendicular to edge)</td>
</tr>
<tr>
<td>Check Item</td>
<td>Classification</td>
<td>Criteria</td>
</tr>
<tr>
<td>------------------------------------------------</td>
<td>----------------</td>
<td>----------------------------------------------------</td>
</tr>
<tr>
<td>Panel Crack</td>
<td>Minor</td>
<td>Any crack is not allowable.</td>
</tr>
<tr>
<td>Copper Exposed (Even Pin or Film)</td>
<td>Minor</td>
<td>Not Allowable by Naked Eye Inspection</td>
</tr>
<tr>
<td>Film or Trace Damage</td>
<td>Minor</td>
<td></td>
</tr>
<tr>
<td>Terminal Lead Prober Mark</td>
<td>Acceptable</td>
<td></td>
</tr>
<tr>
<td>Glue or Contamination on Pin</td>
<td>Minor</td>
<td></td>
</tr>
<tr>
<td>Glue or Contamination on Pin (Couldn’t Be Removed by Alcohol)</td>
<td>Minor</td>
<td></td>
</tr>
<tr>
<td>Ink Marking on Back Side of panel (Exclude on Film)</td>
<td>Acceptable</td>
<td>Ignore for Any</td>
</tr>
</tbody>
</table>
6.3.2 Cosmetic Check (Display Off) in Active Area

It is recommended to execute in clear room environment (class 10k) if actual in necessary.

<table>
<thead>
<tr>
<th>Check Item</th>
<th>Classification</th>
<th>Criteria</th>
</tr>
</thead>
<tbody>
<tr>
<td>Any Dirt &amp; Scratch on Polarizer’s Protective Film</td>
<td>Acceptable</td>
<td>Ignore for not Affect the Polarizer</td>
</tr>
<tr>
<td>Scratches, Fiber, Line-Shape Defect (On Polarizer)</td>
<td>Minor</td>
<td>Ignore if W ≤ 0.1</td>
</tr>
<tr>
<td></td>
<td></td>
<td>W &gt; 0.1</td>
</tr>
<tr>
<td></td>
<td></td>
<td>L ≤ 2</td>
</tr>
<tr>
<td></td>
<td></td>
<td>L &gt; 2</td>
</tr>
<tr>
<td>Dirt, Black Spot, Foreign Material, (On Polarizer)</td>
<td>Minor</td>
<td>Ignore if 0.1 &lt; Φ ≤ 0.25</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Φ ≤ 0.1</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.25 &lt; Φ</td>
</tr>
<tr>
<td>Dent, Bubbles, White spot (Any Transparent Spot on Polarizer)</td>
<td>Minor</td>
<td>Ignore if Φ ≤ 0.5</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Φ &gt; 0.5</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Ignore if no Influence on Display</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.5 &lt; Φ</td>
</tr>
<tr>
<td></td>
<td></td>
<td>n = 0</td>
</tr>
<tr>
<td>Fingerprint, Flow Mark (On Polarizer)</td>
<td>Minor</td>
<td>Not Allowable</td>
</tr>
</tbody>
</table>

* Protective film should not be tear off when cosmetic check.
** Definition of W & L & Φ (Unit: mm): Φ = (a + b) / 2
### 6.3.3 Pattern Check (Display On) in Active Area

<table>
<thead>
<tr>
<th>Check Item</th>
<th>Classification</th>
<th>Criteria</th>
</tr>
</thead>
<tbody>
<tr>
<td>No Display</td>
<td>Major</td>
<td><img src="image" alt="No Display" /></td>
</tr>
<tr>
<td>Missing Line</td>
<td>Major</td>
<td><img src="image" alt="Missing Line" /></td>
</tr>
<tr>
<td>Pixel Short</td>
<td>Major</td>
<td><img src="image" alt="Pixel Short" /></td>
</tr>
<tr>
<td>Darker Pixel</td>
<td>Major</td>
<td><img src="image" alt="Darker Pixel" /></td>
</tr>
<tr>
<td>Wrong Display</td>
<td>Major</td>
<td><img src="image" alt="Wrong Display" /></td>
</tr>
<tr>
<td>Un-uniform</td>
<td>Major</td>
<td><img src="image" alt="Un-uniform" /></td>
</tr>
</tbody>
</table>
### 7. Package Specifications

<table>
<thead>
<tr>
<th>Item</th>
<th>Quantity</th>
</tr>
</thead>
<tbody>
<tr>
<td>Module</td>
<td>810 per Primary Box</td>
</tr>
<tr>
<td>Holding Trays (A)</td>
<td>15 per Primary Box</td>
</tr>
<tr>
<td>Total Trays (B)</td>
<td>16 per Primary Box (Including 1 Empty Tray)</td>
</tr>
<tr>
<td>Primary Box (C)</td>
<td>1–4 per Carton (4 as Major / Maximum)</td>
</tr>
</tbody>
</table>
8. Precautions When Using These OEL Display Modules

8.1 Handling Precautions

1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
3) If pressure is applied to the display surface or its neighborhood of the OEL display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
4) The polarizer covering the surface of the OEL display module is soft and easily scratched. Please be careful when handling the OEL display module.
5) When the surface of the polarizer of the OEL display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
   * Scotch Mending Tape No. 810 or an equivalent
   Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.
   Also, pay attention that the following liquid and solvent may spoil the polarizer:
   * Water
   * Ketone
   * Aromatic Solvents
6) Hold OEL display module very carefully when placing OEL display module into the system housing. Do not apply excessive stress or pressure to OEL display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.
7) Do not apply stress to the driver IC and the surrounding molded sections.
8) Do not disassemble nor modify the OEL display module.
9) Do not apply input signals while the logic power is off.
10) Pay sufficient attention to the working environments when handing OEL display modules to prevent occurrence of element breakage accidents by static electricity.
    * Be sure to make human body grounding when handling OEL display modules.
    * Be sure to ground tools to use or assembly such as soldering irons.
    * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
    * Protective film is being applied to the surface of the display panel of the OEL display module. Be careful since static electricity may be generated when exfoliating the protective film.
11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OEL display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5).
12) If electric current is applied when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.
8.2 Storage Precautions

1) When storing OEL display modules, put them in static electricity preventive bags avoiding exposure to direct sunlight nor to lights of fluorescent lamps and, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Allvision technology Inc.) At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.

2) If electric current is applied when water drops are adhering to the surface of the OEL display module, when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

8.3 Designing Precautions

1) The absolute maximum ratings are the ratings which cannot be exceeded for OEL display module, and if these values are exceeded, panel damage may be happen.

2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the $V_{IL}$ and $V_{IH}$ specifications and, at the same time, to make the signal line cable as short as possible.

3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit ($V_{DD}$).

4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.

5) As for EMI, take necessary measures on the equipment side basically.

6) When fastening the OEL display module, fasten the external plastic housing section.

7) If power supply to the OEL display module is forcibly shut down by such errors as taking out the main battery while the OEL display panel is in operation, we cannot guarantee the quality of this OEL display module.

8) The electric potential to be connected to the rear face of the IC chip should be as follows: SH1107
   * Connection (contact) to any other potential than the above may lead to rupture of the IC.

8.4 Precautions when disposing of the OEL display modules

1) Request the qualified companies to handle industrial wastes when disposing of the OEL display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

8.5 Other Precautions

1) When an OEL display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur. Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.

2) To protect OEL display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OEL display modules.
   * Pins and electrodes
   * Pattern layouts such as the FPC

3) With this OEL display module, the OEL driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OEL driver is exposed to light, malfunctioning may occur.
   * Design the product and installation method so that the OEL driver may be shielded from light in actual usage.
   * Design the product and installation method so that the OEL driver may be shielded from light during the inspection processes.

4) Although this OEL display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may
be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.

5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.